



APTPEP1.40CP2DC (formerly APTLTD.40CP2DC)

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Gerald A. Hutchinson, et. al  
Appl. No. : 10/788,905  
Filed : February 26, 2004  
For : PREFORM MOLDS  
INCORPORATING HIGH HEAT  
CONDUCTIVITY MATERIAL  
Examiner : Timothy W. Heitbrink

Group Art Unit 1722

**AMENDMENT AND RESPONSE TO JANUARY 30, 2006 OFFICE ACTION**

Mail Stop Amendment  
U.S. Patent and Trademark Office  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the January 30, 2006 Office Action, Applicant requests the Examiner to reconsider the above-identified patent application in view of the following amendments and remarks.

**Amendments to the Claims:** Begin on page 2 of this Response.

**Remarks:** Begin on page 6 of this Response.